



BSI Standards Publication

Semiconductor devices — Mechanical and climatic test methods

Part 37: Board level drop test method using an accelerometer

National foreword

This British Standard is the UK implementation of EN 60749-37:2022. It is identical to IEC 60749-37:2022. It supersedes BS EN 60749-37:2008, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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© The British Standards Institution 2022
Published by BSI Standards Limited 2022

ISBN 978 0 539 15199 2

ICS 31.080.01

Compliance with a British Standard cannot confer immunity from legal obligations.

This British Standard was published under the authority of the Standards Policy and Strategy Committee on 30 November 2022.

Amendments/corrigenda issued since publication

Date

Text affected

English Version

Semiconductor devices - Mechanical and climatic test methods -
Part 37: Board level drop test method using an accelerometer
(IEC 60749-37:2022)

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 37: Méthode d'essai de
chute au niveau de la carte avec utilisation d'un
accéléromètre
(IEC 60749-37:2022)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 37: Prüfverfahren Fall der Leiterplatte
unter Verwendung eines Beschleunigungs-Messgerätes
(IEC 60749-37:2022)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47/2651/CDV, future edition 2 of IEC 60749-37, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-37:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2023-08-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2025-11-16

This document supersedes EN 60749-37:2008 and all of its amendments and corrigenda (if any).

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The text of the International Standard IEC 60749-37:2022 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 60749-40 NOTE Harmonized as EN 60749-40

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-10	2022	Semiconductor devices - Mechanical and climatic test methods - Part 10: Mechanical shock - device and subassembly	EN IEC 60749-10	2022
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN IEC 60749-20	-
IEC 60749-20-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat	EN 60749-20-1	-

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